

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free):   XC8109xxxxER-G  
Typical Mass:           6       mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.440	Silicon	73400	7440-21-3
		- Arsenic	<1	7440-38-2
Lead pad	1.100	Nickel	183400	7440-02-0
		Silver	14600	7440-22-4
		Gold	2700	7440-57-5
Die attach	0.020	Epoxy Resin	3300	—
		Silica	2700	60676-86-0
Bonding wire	0.118	Gold	19700	7440-57-5
Resin	3.781	Silica	630200	60676-86-0
		Epoxy Resin	38500	—
		Phenol Resin	31500	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."